BENDING AND FORMING METHOD OF FABRICATING EXPOSED LEADFRAMES FOR SEMICONDUCTOR DEVICES

ABSTRACT

The invention relates to a single piece leadframe that can be used in current semiconductor device production. The leadframe has a plurality of segments in a horizontal plane, a chip mount pad in a different horizontal plane, and another plurality of segments connecting said chip mount pad with said leadframe. The latter plurality of segments has a geometry designed so as to tolerate bending and stretching beyond the limit of simple elongation based upon the inherent material characteristics. The chip mount pad of said leadframe provides direct thermal contact to an external heat conductor or heat sink by being designed so as to extend through the encapsulating package. The exposed chip pad can also be used electrically as a ground connection.

Figure 1A

This Sheet Has Been Replaced

